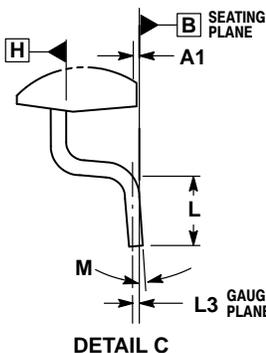
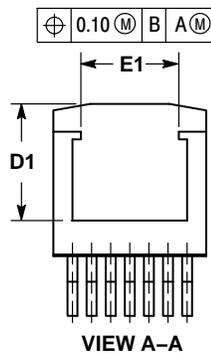
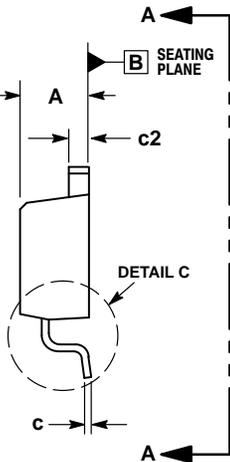
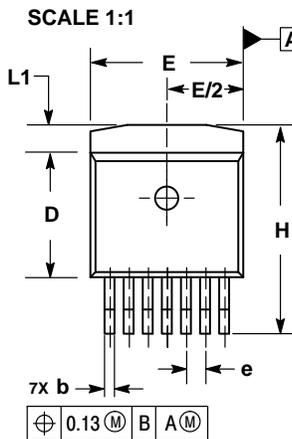
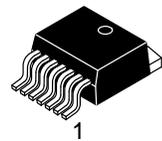


D<sup>2</sup>PAK-7 (SHORT LEAD)  
CASE 936AB  
ISSUE B

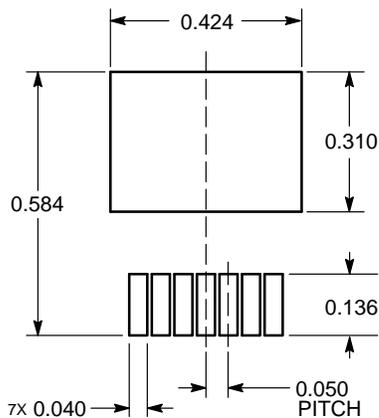
DATE 08 SEP 2009



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: INCHES.
  3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH AND GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.005 MAXIMUM PER SIDE. THESE DIMENSIONS TO BE MEASURED AT DATUM H.
  4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E, L1, D1, AND E1. DIMENSIONS D1 AND E1 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THE THERMAL PAD.

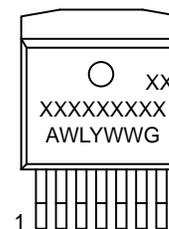
| DIM | INCHES    |       | MILLIMETERS |       |
|-----|-----------|-------|-------------|-------|
|     | MIN       | MAX   | MIN         | MAX   |
| A   | 0.170     | 0.180 | 4.32        | 4.57  |
| A1  | 0.000     | 0.010 | 0.00        | 0.25  |
| b   | 0.026     | 0.036 | 0.66        | 0.91  |
| c   | 0.017     | 0.026 | 0.43        | 0.66  |
| c2  | 0.045     | 0.055 | 1.14        | 1.40  |
| D   | 0.325     | 0.368 | 8.25        | 9.53  |
| D1  | 0.270     | ---   | 6.86        | ---   |
| E   | 0.380     | 0.420 | 9.65        | 10.67 |
| E1  | 0.245     | ---   | 6.22        | ---   |
| e   | 0.050 BSC |       | 1.27 BSC    |       |
| H   | 0.539     | 0.579 | 13.69       | 14.71 |
| L   | 0.058     | 0.078 | 1.47        | 1.98  |
| L1  | ---       | 0.066 | ---         | 1.68  |
| L3  | 0.010 BSC |       | 0.25 BSC    |       |
| M   | 0°        | 8°    | 0°          | 8°    |

RECOMMENDED  
SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

GENERIC  
MARKING DIAGRAM\*



- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

|                  |                                   |  |
|------------------|-----------------------------------|--|
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| DESCRIPTION:     | D <sup>2</sup> PAK-7 (SHORT LEAD) | PAGE 1 OF 1  |

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